

## MEZALOK HIGH-SPEED LOW-FORCE XMC CONNECTOR

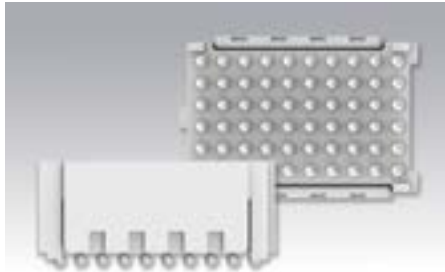
---

FASTER SPEED (32+ Gb/s) AND LOWER FORCE

# Mezalok High-Speed Low-Force XMC Connector



Faster speed (32+ Gb/s) and lower force



## FAST

- Capable of speeds 32+ Gb/s with VITA 42.3 pin out

## REFINED

- Unmating force reduction: 47%
- Mating force reduction: 32%
- Rugged dual point contact system
- Maintains ball grid array (BGA) PCB attachment, supports standard surface mount processing

## RUGGED

- Designed for highly rugged performance rating—meeting legacy Mezalok specification
- Testing to VITA 72 working group environment
- Thermal stability for reliable solder joints—testing to 2000 thermal cycles, -55°C to +125°C

## COMPATIBLE / UPGRADEABLE

- Compliant with VITA 61 and 42 standards, Mezalok High-Speed Low-Force (HSLF) socket assemblies are intermateable with legacy Mezalok pin connectors allowing ease of upgrade

## FLEXIBLE

- Multiple positions and stack heights available

## APPLICATIONS/MARKETS SERVED

- Aircraft
- Ground Vehicle
- Sea
- Space
- Missile Defense

## Description

TE Connectivity's (TE) Mezalok High-Speed Low-Force (HSLF) XMC connectors are designed for mezzanine applications for rugged embedded computing interconnects.

The connectors utilize a rugged dual point contact system that meets the qualification requirements of legacy Mezalok high speed connectors.

The connectors are available in 60, 114, and 320 positions with stack height options of 10, 12, 17 and 18 mm.

Mezalok High-Speed Low-Force XMC connectors meet the same rugged standards as listed in VITA 47 and VITA 72. The 114-position connector is compliant to VITA 61 and additional positions and stack heights are available.

These High-Speed Low-Force connectors feature a wide operating temperature range, excellent thermal stability, and data rates to 32+ Gb/s, with VITA 42.3 pinout.

Mezalok high-speed low-force connectors utilize the reliable ball grid array printed circuit board surface mount application.

## SPECIFICATIONS

- **Product Specification:** 108-2411
- **Application Specification:** 114-13279
- **Qualification Test Report:** 501-736
- **HSLF Qualification Test Report:** 501-134111
- **Electrical Performance Report:** 505-4
- **White Paper:** Mezalok White Paper

# Mezalok High-Speed Low-Force XMC Connector

## PART NUMBER LIST

		Low Mating / Extraction Force						
Position Size	Connector and Stack Height (mm)		50 Microinch Gold Mating		50 Microinch Gold Mating		30 Microinch Gold Mating	
			Tin-Lead BGA	Lead Free BGA	Tin-Lead BGA	Lead Free BGA	Tin-Lead BGA	Lead Free BGA
60	Pin Connector		2102079-1	2102079-2	2102079-1	2102079-2		
	Socket Connector	10	2369022-1	2369022-2	2102080-1			
		12	2369022-3	2369022-4	2102080-3			
114	Pin Connector		2102060-1	2102060-2	2102060-1	2102060-2	2102060-3	2102060-4
	Socket Connector	10	2355825-1	2355825-2	2102061-1	2102061-2	2102061-5	2102061-6
		12	2355825-3	2355825-4	2102061-3	2102061-4	2102061-7	2102061-8
		15			1-2102061-3	1-2102061-4	1-2102061-5	1-2102061-6
		17	1-2355825-7	1-2355825-8	1-2102061-7	1-2102061-8		
		18	2355825-9	1-2355825-0	2102061-9	1-2102061-0	1-2102061-1	1-2102061-2
320	Pin Connector		2102429-1		2102429-1			2102429-4
	Socket Connector	10	2355827-1	2355827-2	2102430-1			2102430-6
		18	2355827-9	1-2355827-0	2102430-9			1-2102430-2

Empower Engineers to Solve Problems, Moving the World Forward.

AMP | AGASTAT | CII | DEUTSCH | DRI | HARTMAN | KILOVAC  
MICRODOT | NANONICS | POLAMCO | Raychem | Rochester | SEACON

## CONNECT WITH US

We make it easy to connect with our experts and are ready to provide all the support you need. Visit [te.com/support](https://te.com/support) to chat with a Product Information Specialist.

## QUALITY STARTS WITH THE RIGHT APPLICATION TOOLING

Creating a quality crimp connection is essential to delivering high performance and reliability in extreme environments. From low to high volume wire processing, TE has you covered with a full range of application tooling and a global field service team.

- [View all application tooling](#)
- [Connect with our experts to find the right tool for your application](#)

### [te.com/mezalok-hs-lf](https://te.com/mezalok-hs-lf)

AMP, AGASTAT, CII, DEUTSCH, DRI, HARTMAN, KILOVAC, Mezalok, MICRODOT, NANONICS, POLAMCO, Raychem, Rochester, SEACON, TE, TE Connectivity, and TE connectivity (logo) are trademarks owned or licensed by TE Connectivity. All other logos, products and/or company names referred to herein might be trademarks of their respective owners.

The information given herein, including drawings, illustrations and schematics which are intended for illustration purposes only, is believed to be reliable. However, TE Connectivity makes no warranties as to its accuracy or completeness and disclaims any liability in connection with its use. TE Connectivity's obligations shall only be as set forth in TE Connectivity's Standard Terms and Conditions of Sale for this product and in no case will TE Connectivity be liable for any incidental, indirect or consequential damages arising out of the sale, resale, use or misuse of the product. Users of TE Connectivity products should make their own evaluation to determine the suitability of each such product for the specific application.

© 2021 TE Connectivity All Rights Reserved.

2396725-1 08/21

### MEZALOK HIGH-SPEED LOW-FORCE XMC CONNECTOR

TE Connectivity  
Aerospace, Defense & Marine  
2900 Fulling Mill Road  
Middletown, PA 17057